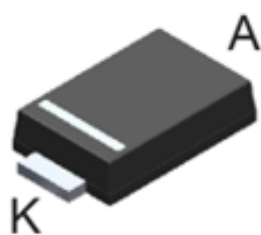



Automotive 3 A - 100 V power Schottky rectifier



SMB Flat

Features

- AEC-Q101 qualified revision C 
- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche capability specified
- ECOPACK2 compliant
- PPAP capable
- V_{RRM} guaranteed from -40 to +175 °C

Applications

- DC/DC converter
- Reverse polarity protection
- Freewheeling diodes
- Switching diode

Description

This Schottky rectifier is packaged in SMB Flat designed for high frequency miniature switched mode power supplies such as adaptors and on board DC to DC converters for automotive applications.

Product status link

[STPS3H100-Y](#)

Product summary

$I_{F(AV)}$	3 A
V_{RRM}	100 V
T_J (max.)	175 °C
V_F (typ.)	0.63 V

1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage, $T_j = -40\text{ °C}$ to $+175\text{ °C}$		100	V
$I_{F(AV)}$	Average forward current, $\delta = 0.5$ square wave	$T_l = 125\text{ °C}$	3	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	25	A
P_{ARM}	Repetitive peak avalanche power	$t_p = 10\text{ }\mu\text{s}$, $T_j = 125\text{ °C}$	170	W
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature range ⁽¹⁾		-40 to +175	°C

1. $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameter

Symbol	Parameter	Typ. value	Unit
$R_{th(j-l)}$	Junction to lead	15	°C/W

For more information, please refer to the following application note:

- AN5088: Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		1.00	μA
		$T_j = 125\text{ °C}$		-	0.40	1.00	mA
		$T_j = 150\text{ °C}$		-		3.3	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 3\text{ A}$	-		0.84	V
		$T_j = 125\text{ °C}$		-	0.63	0.68	
		$T_j = 25\text{ °C}$	$I_F = 6\text{ A}$	-		0.94	
		$T_j = 125\text{ °C}$		-	0.71	0.80	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 0.56 \times I_{F(AV)} + 0.04 \times I_F^2(RMS)$$

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current

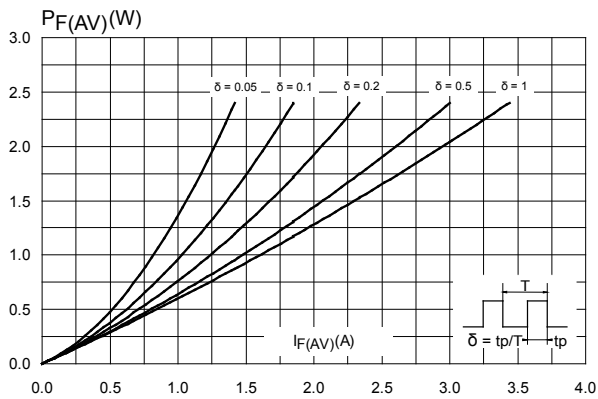


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

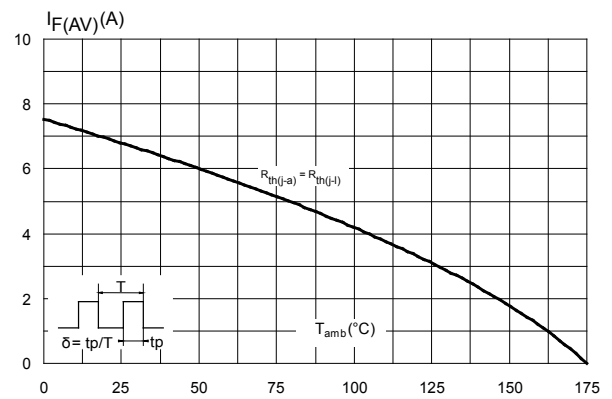


Figure 3. Normalized avalanche power derating versus junction temperature ($T_j = 125^\circ\text{C}$)

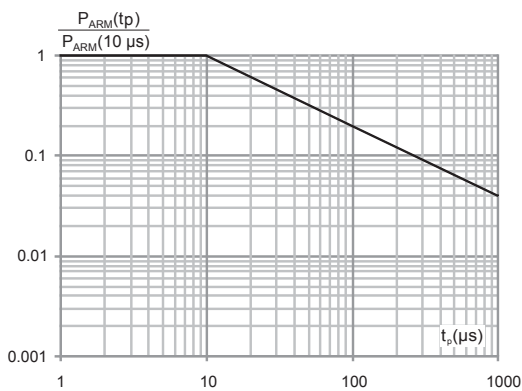


Figure 4. Relative variation of thermal impedance junction to lead versus pulse duration

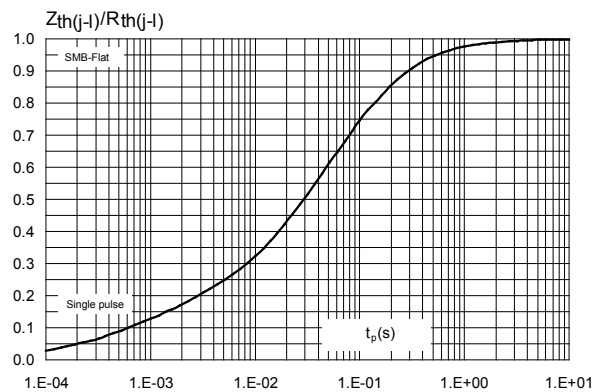
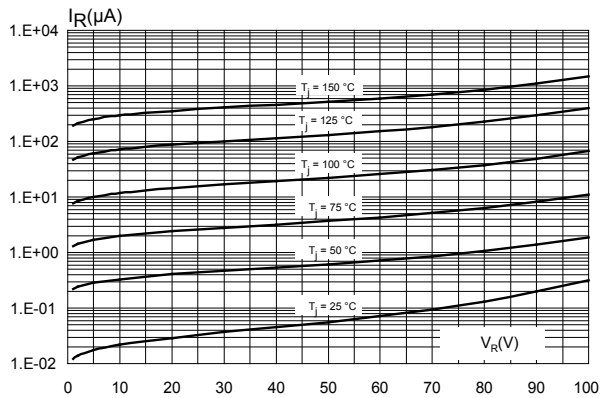
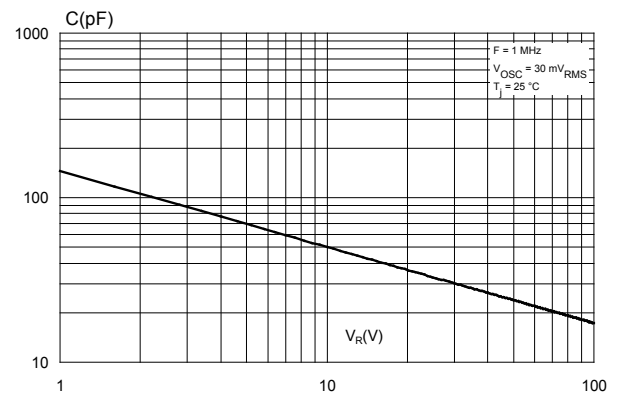
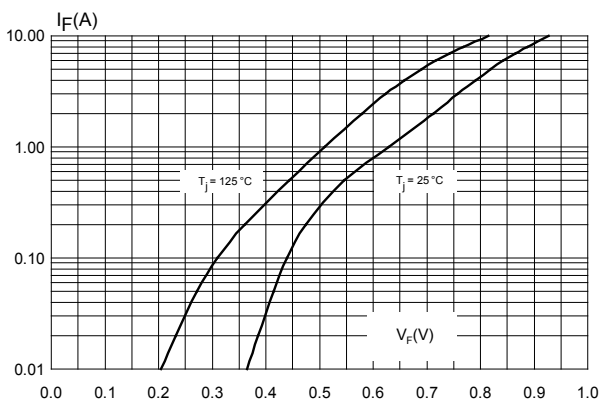
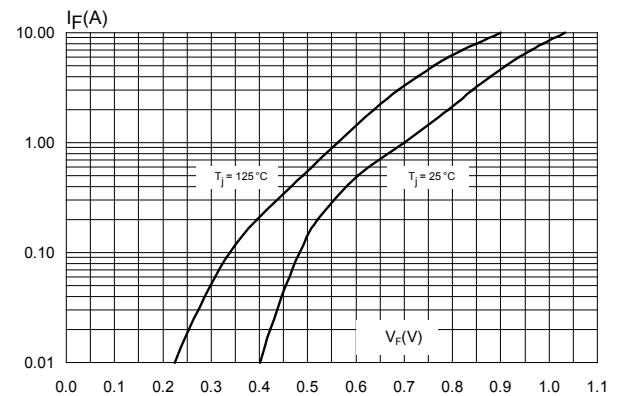
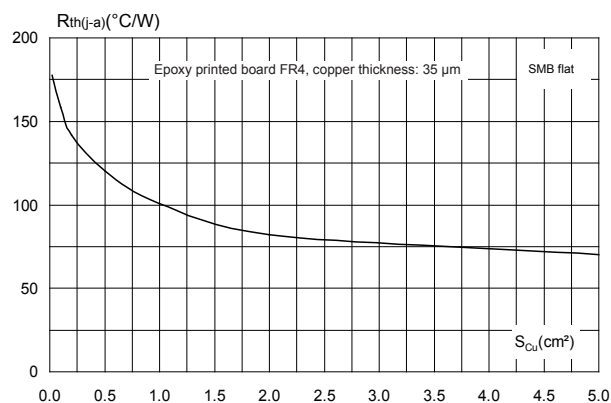


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

Figure 6. Junction capacitance versus reverse voltage applied (typical values)

Figure 7. Forward voltage drop versus forward current (typical values)

Figure 8. Forward voltage drop versus forward current (maximum values)

Figure 9. Thermal resistance junction to ambient versus copper surface under each lead (SMB flat, typical values)


2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SMB Flat package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 10. SMB Flat package outline

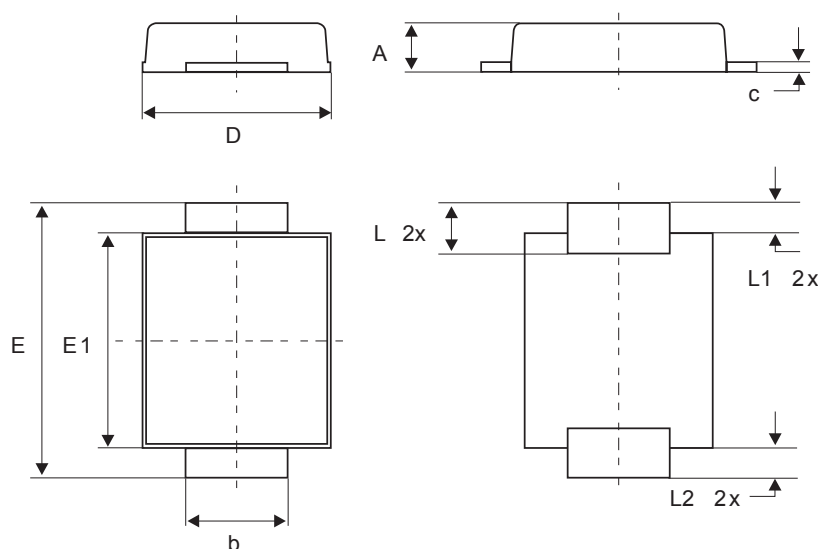
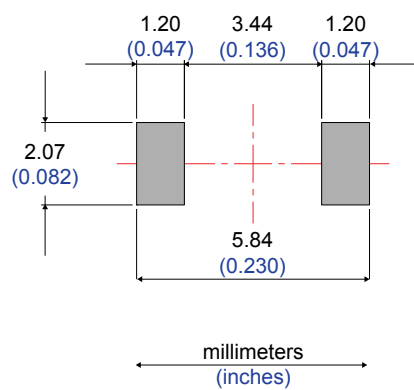


Table 4. SMB Flat mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.043
b	1.95		2.20	0.077		0.087
c	0.15		0.40	0.006		0.016
D	3.30		3.95	0.130		0.156
E	5.10		5.60	0.201		0.220
E1	4.05		4.60	0.159		0.181
L	0.75		1.50	0.030		0.059
L1		0.40			0.016	
L2		0.60			0.024	

Figure 11. Footprint recommendations, dimensions in mm (inches)



3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS3H100UFY	3H100Y	SMB Flat	0.050 g	5000	Tape and reel

Revision history

Table 6. Document revision history

Date	Version	Changes
07-Nov-2016	1	Initial release.
14-Jan-2020	2	Updated Figure 3 . Minor text changes to improve readability.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2020 STMicroelectronics – All rights reserved